

FAST - [Untitled1:1]

FileViewEditToolsWindowHelp

Drafts

Pending

Active

Failed

L1: (191) 257/686.ccls. and row

L2: (849) 257/686.ccls. and (terminals or leads or pins)

L3: (13) ("5138438" | "5677569" | "5744827" | "5994166" | "6051878" | "RE

L4: (43) ("3851221" | "4103318" | "4361261" | "4444349" | "4586642" | "473

Search

DBs

USPAT: EPO: JPO: DERWENT: USOCR

Default operator: OR

Pulse

Highlight all hit terms initially

257/686.ccls. and (terminals or leads or pins)

BRG term

S&R term

Image

Text

HTML

	U	Document ID	Issue Dat	Page	Title	Current OR	Current XRe	Retrieval	Inventor	S	C	P	2	3	4	5	6	7	8	9	0
1	<input type="checkbox"/>	US 6707684 R1	20040316	8	Method and apparatus for direct connection between t	361/785	257/686; 257/686	257/686	Andric, Anthony M. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2	<input type="checkbox"/>	US 6707143 R2	20040316	12	Stacked semiconductor chip attached to a wiring ha	257/686	257/678; 257/685	257/686	Fujimoto, Hiroaki et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3	<input type="checkbox"/>	US 6707142 R2	20040316	16	Package stacked semiconductor device havin	257/686	257/697	257/686	Jeong, Do-Soo et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
4	<input type="checkbox"/>	US 6707141 R2	20040316	13	Multi-chip module substrate for use with leads over chip t	257/686	257/673; 257/679	257/686	Akram, Salman	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
5	<input type="checkbox"/>	US 6707140 R1	20040316	14	Arrayable, scaleable, and stackable molded package n	257/686	257/777; 257/778	257/686	Nguyen, Luu et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6	<input type="checkbox"/>	US 6706971 R2	20040316	12	Stackable microcircuit layer formed from a plastic encan	174/255	174/251; 174/522	257/686	Albert, Douglas M. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
7	<input type="checkbox"/>	US 6705877 R1	20040316	15	Stackable memory module with variable bandwidth	439/74	257/686; 356/52	257/686	Li, Che-yu et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8	<input type="checkbox"/>	US 6703651 R2	20040309	9	Electronic device having stacked modules and metho	257/209	257/529; 257/685	257/686	Worz, Andreas et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
9	<input type="checkbox"/>	US 6700178 R2	20040302	6	Package of a chip with beveled edges	257/618	257/686; 257/723	257/686	Chen, Jian-Cheng et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
10	<input type="checkbox"/>	US 6697259 R1	20040224	16	Circuit board of protective circuit for storage battery n	361/752	257/685; 257/686	257/686	Nakamura, Satoshi	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
11	<input type="checkbox"/>	US 6693347 R2	20040217	11	Semiconductor device	257/686	257/678; 257/685	257/686	Fujimoto, Hiroaki et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
12	<input type="checkbox"/>	US 6693346 R2	20040217	34	Semiconductor memory module having double-sided	257/685	257/686; 257/723	257/686	Masayuki, Watanabe et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
13	<input type="checkbox"/>	US 6690089 R2	20040210	9	Semiconductor device having multi-chip package	257/686	257/685; 257/777	257/686	Uchida, Yasufumi	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
14	<input type="checkbox"/>	US 6690088 R2	20040210	10	Integrated circuit package stacking structure	257/686	257/491; 257/686	257/686	MacIntyre, Donald M.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
15	<input type="checkbox"/>	US 6690087 R2	20040210	13	Power semiconductor module ceramic substrate wi	257/686	257/177; 257/684	257/686	Kobayashi, Takatoshi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
16	<input type="checkbox"/>	US 6686768 R2	20040203	67	Electrically-programmable interconnect architecture fo	326/38	257/686; 326/101	257/686	Comer, Alan Elbert	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
17	<input type="checkbox"/>	US 6686663 R2	20040203	20	Semiconductor device and a method of manufacturing the	257/777	257/676; 257/686	257/686	Masuda, Masachika et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
18	<input type="checkbox"/>	US 6686655 R2	20040203	19	Low profile multi-IC chip package connector	257/686	257/685; 257/723	257/686	Moden, Walter L. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
19	<input type="checkbox"/>	US 6686654 R2	20040203	18	Multiple chip stack structure	257/686	257/685; 257/723	257/686	Farrar, Paul A. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

Ready

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